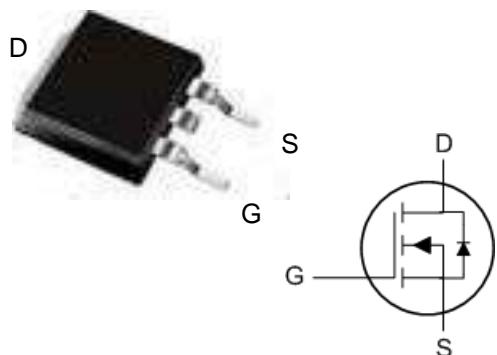


AUTOMOTIVE N-Ch 40V Fast Switching MOSFETs

Description:

- Advanced Trench MOS Technology
- Low Gate Charge
- Low $R_{DS(ON)}$
- 100% EAS Guaranteed
- Green Device Available
- AEC-Q101 qualified and PPAP capable

TO-252 Pin Configuration



Applications:

- SMPS Synchronous Rectification
- DC/DC Converters
- Or-ing



AEC-Q101 Qualified

Product Summary

| BVDSS | RDS(on) | ID |
|-------|---------|------|
| 40V | 2.6mΩ | 100A |

Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|---------------------------|--|------------|-------|
| V_{DS} | Drain-Source Voltage | 40 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| $I_D @ T_C = 25^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^{1,6}$ | 100 | A |
| $I_D @ T_C = 100^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^{1,6}$ | 89 | A |
| I_{DM} | Pulsed Drain Current ² | 400 | A |
| EAS | Single Pulse Avalanche Energy ³ | 320 | mJ |
| I_{AS} | Avalanche Current | 80 | A |
| $P_D @ T_C = 25^\circ C$ | Total Power Dissipation ⁴ | 83 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | °C |
| T_J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient ¹ | --- | 50 | °C/W |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case ¹ | --- | 1.5 | °C/W |



Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|------------------------------|--|---|------|------|-----------|------------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=250\mu\text{A}$ | 40 | --- | --- | V |
| $R_{\text{DS(ON)}}$ | Static Drain-Source On-Resistance ² | $V_{\text{GS}}=10\text{V}$, $I_{\text{D}}=20\text{A}$ | --- | 2.0 | 2.6 | $\text{m}\Omega$ |
| $V_{\text{GS(th)}}$ | Gate Threshold Voltage | $V_{\text{GS}}=V_{\text{DS}}$, $I_{\text{D}}=250\mu\text{A}$ | 2 | 2.8 | 3.6 | V |
| I_{DSS} | Drain-Source Leakage Current | $V_{\text{DS}}=32\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^{\circ}\text{C}$ | --- | --- | 1 | μA |
| | | $V_{\text{DS}}=32\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^{\circ}\text{C}$ | --- | --- | 5 | |
| I_{GSS} | Gate-Source Leakage Current | $V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$ | --- | --- | ± 100 | nA |
| g_{fs} | Forward Transconductance | $V_{\text{DS}}=5\text{V}$, $I_{\text{D}}=20\text{A}$ | --- | 53 | --- | S |
| R_g | Gate Resistance | $V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$ | --- | 1.9 | --- | Ω |
| Q_g | Total Gate Charge | $V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_{\text{D}}=20\text{A}$ | --- | 60 | --- | nC |
| Q_{gs} | Gate-Source Charge | | --- | 14.7 | --- | |
| Q_{gd} | Gate-Drain Charge | | --- | 13.9 | --- | |
| $T_{\text{d(on)}}$ | Turn-On Delay Time | $V_{\text{DD}}=20\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=1.5\Omega$, $I_{\text{D}}=20\text{A}$ | --- | 11.4 | --- | ns |
| T_r | Rise Time | | --- | 41.6 | --- | |
| $T_{\text{d(off)}}$ | Turn-Off Delay Time | | --- | 42.8 | --- | |
| T_f | Fall Time | | --- | 27.2 | --- | |
| C_{iss} | Input Capacitance | $V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$ | --- | 3739 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 1267 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 106 | --- | |
| Diode Characteristics | | | | | | |
| I_s | Continuous Source Current ^{1,6} | $V_G=V_D=0\text{V}$, Force Current | --- | --- | 100 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^{\circ}\text{C}$ | --- | --- | 1.2 | V |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=80\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature.
- 5.The data is theoretically the same as I_{D} and I_s , in real applications , should be limited by total power dissipation.
- 6.Package limitation current is 100A.

Typical Characteristics

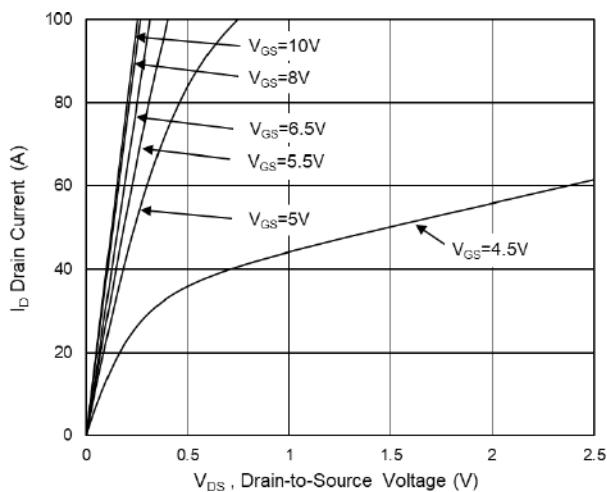


Fig.1 Typical Output Characteristics

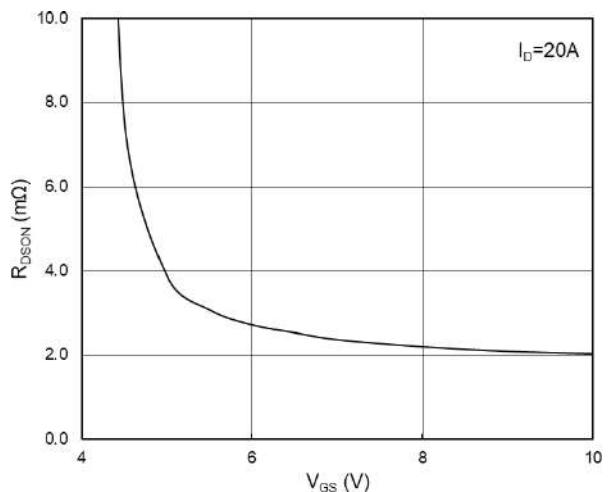


Fig.2 On-Resistance vs G-S Voltage

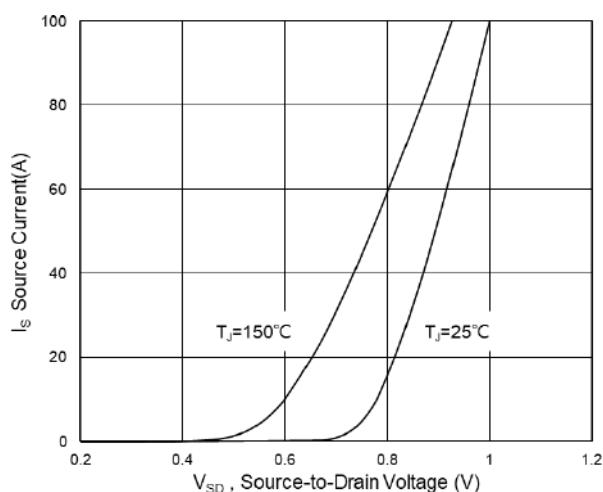


Fig.3 Source Drain Forward Characteristics

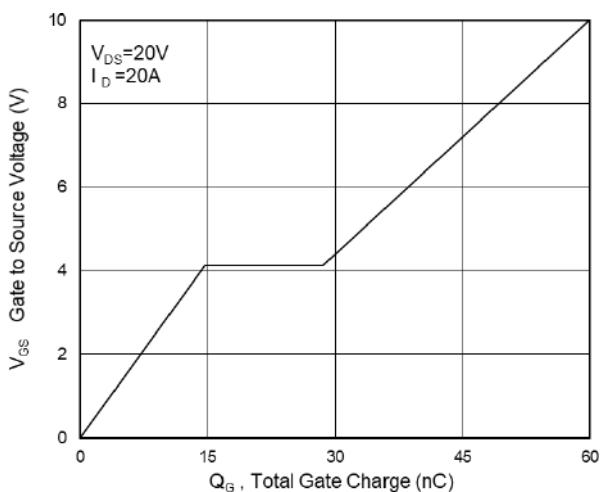


Fig.4 Gate-Charge Characteristics

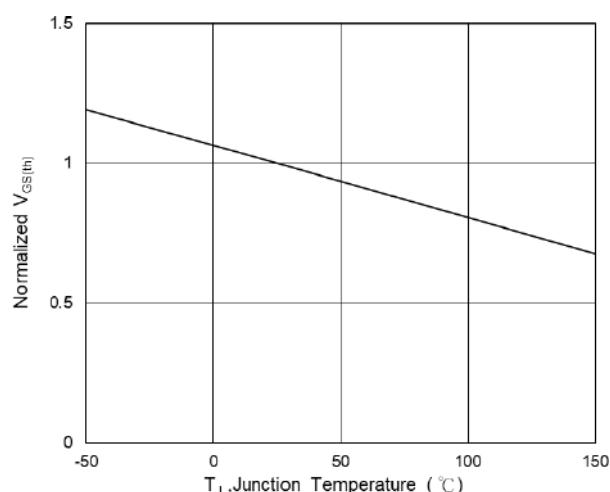


Fig.5 Normalized $V_{GS(th)}$ vs T_J

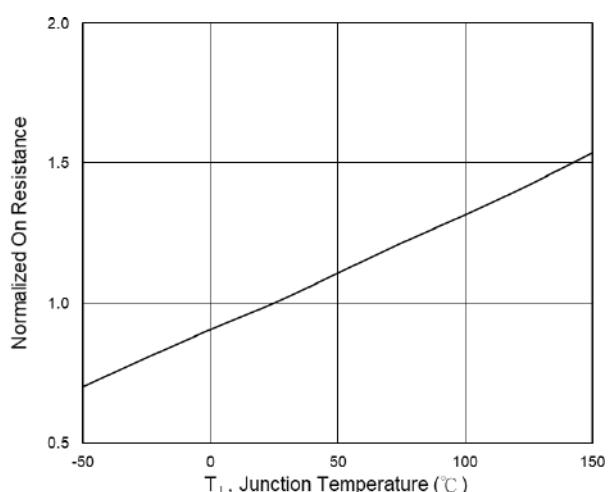


Fig.6 Normalized $R_{DS(on)}$ vs T_J

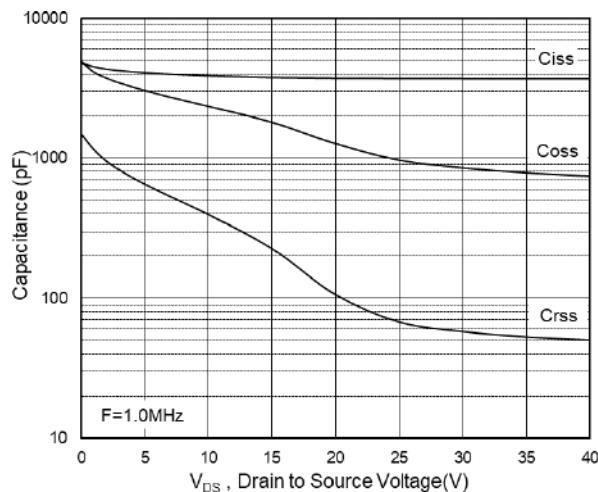


Fig.7 Capacitance

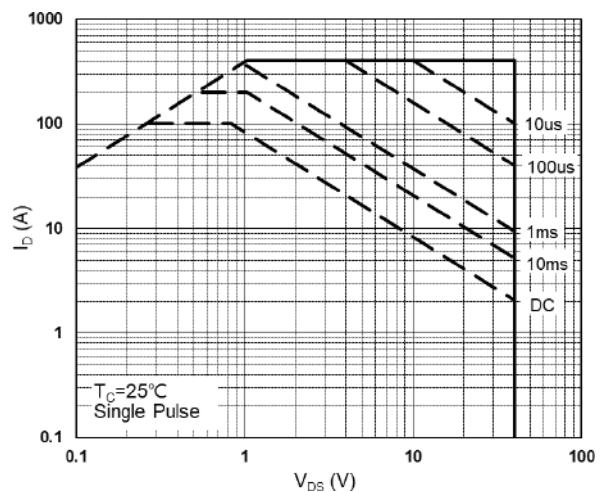


Fig.8 Safe Operating Area

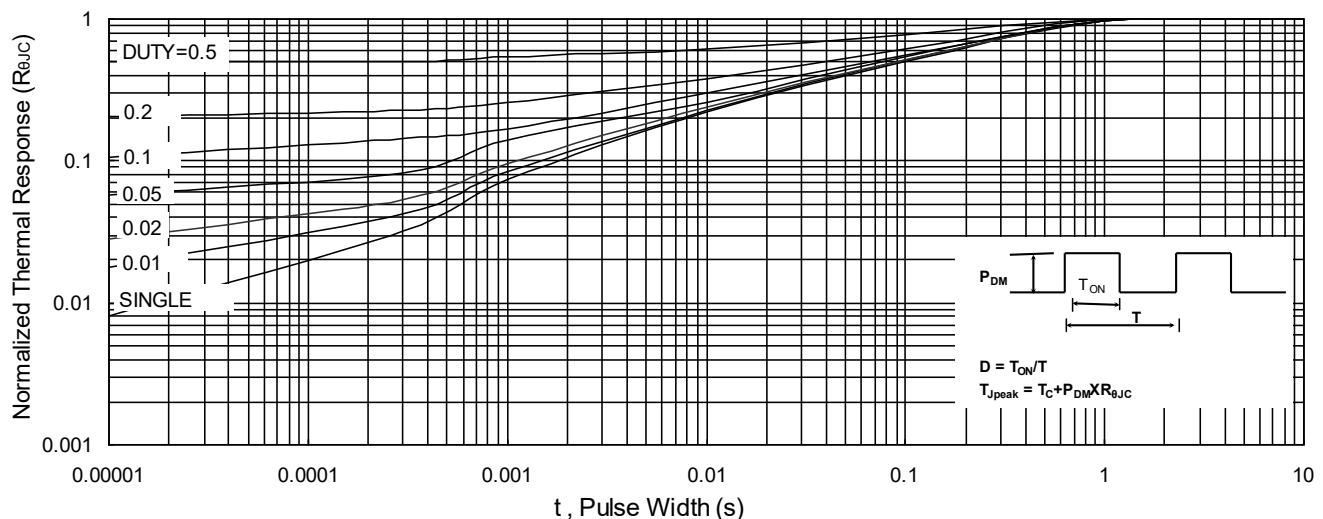


Fig.9 Normalized Maximum Transient Thermal Impedance

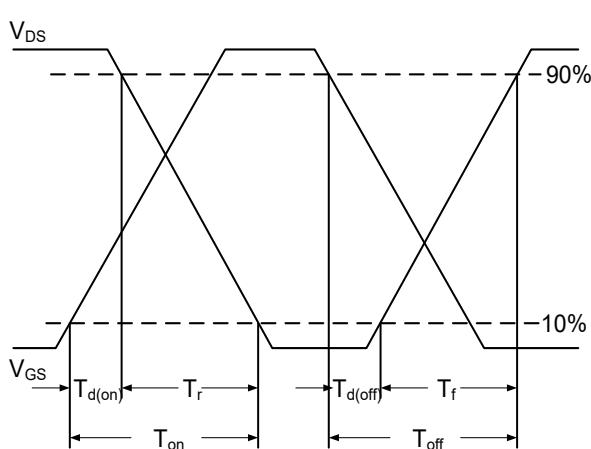


Fig.10 Switching Time Waveform

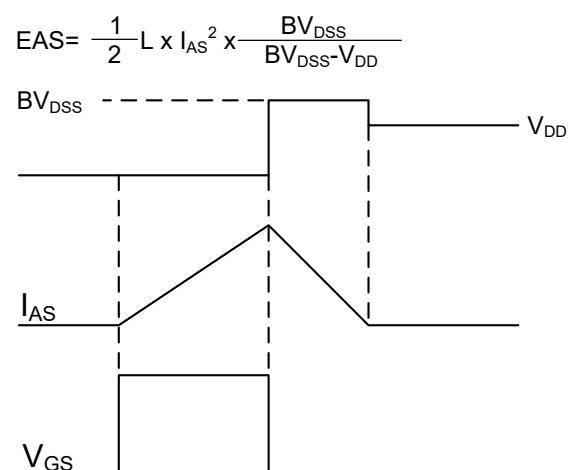
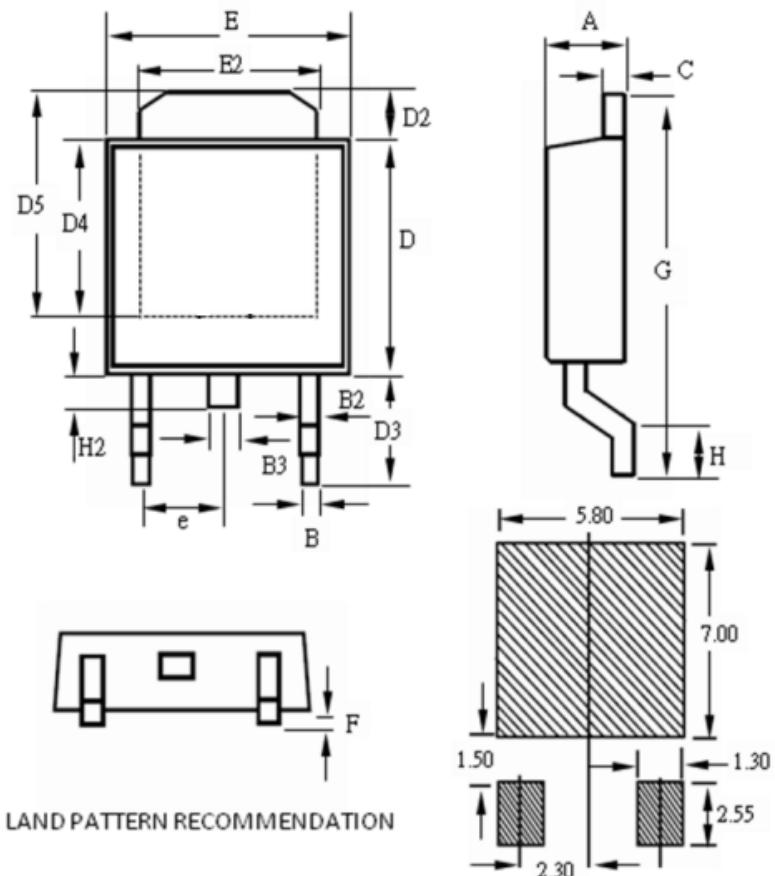


Fig.11 Unclamped Inductive Switching Waveform

TO-252 Package Outline



| SYMBOLS | MILLIMETERS | | | INCHES | | |
|---------|-------------|------|-------|--------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 2.10 | -- | 2.50 | 0.083 | -- | 0.098 |
| B | 0.30 | -- | 0.89 | 0.012 | -- | 0.035 |
| B2 | 0.40 | -- | 1.14 | 0.016 | -- | 0.045 |
| B3 | 0.60 | -- | 1.00 | 0.024 | -- | 0.039 |
| C | 0.40 | -- | 0.89 | 0.016 | -- | 0.035 |
| D | 5.30 | -- | 6.25 | 0.209 | -- | 0.246 |
| D2 | 0.50 | -- | 1.70 | 0.020 | -- | 0.067 |
| D3 | 2.20 | -- | 3.40 | 0.087 | -- | 0.134 |
| D4 | 4.32 | -- | -- | 0.170 | -- | -- |
| D5 | 5.21 | -- | -- | 0.205 | -- | -- |
| E | 6.30 | -- | 6.73 | 0.248 | -- | 0.265 |
| E2 | 4.80 | -- | 5.46 | 0.189 | -- | 0.215 |
| F | 0.00 | -- | 0.30 | 0.000 | -- | 0.012 |
| G | 9.20 | -- | 10.41 | 0.362 | -- | 0.410 |
| H | 0.90 | -- | 1.95 | 0.035 | -- | 0.077 |
| H2 | 0.50 | -- | 1.10 | 0.020 | -- | 0.043 |
| e | -- | 2.30 | -- | -- | 0.091 | -- |